



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-07-25
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giovanni Giacopello	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	AKQ7*UF96JC1	A	BO2A	2014-07-25
Amount	UoM	Unit type	ST ECOPACK Grade	
153.50	mg	Each	ECOPACK® 1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	3,9,9,9,1.25	16	gull wing	
Comment	Package: SO 16 .15 TO JEDEC MS-012; MDF valid for ST26C31BDR			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	AKQ7*UF96JC1					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	1.78	mg	supplier	die	Silicon (Si)	7440-21-3		1.722	mg	967416	11218
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.014	mg	7865	91
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.005	mg	2809	33
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.024	mg	13483	156
die (s)				supplier	passivation	Gamma-butyrolactone	96-48-0		0.01	mg	5618	65
die (s)				supplier	passivation	Polyhydroxyamide	55295-98-2		0.005	mg	2809	33
Leadframe	Copper & its alloys	37.144	mg	supplier	alloy	Copper (Cu)	7440-50-8		35.997	mg	969120	234508
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.847	mg	22803	5518
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.051	mg	1373	332
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.044	mg	1185	287
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.188	mg	5061	1225
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.012	mg	323	78
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.005	mg	135	33
Die attach	Other Organic Materials	0.535	mg	supplier	glue	Silver (Ag)	7440-22-4		0.401	mg	749533	2612
Die attach				supplier	glue	Epoxy Cresol Novolak	29690-82-2		0.132	mg	246729	860
Die attach				supplier	glue	1-Isopropyl-2,2-dimethyltrimethylene diisobut	6846-50-0		0.002	mg	3738	13
Bonding wire	Precious metals	0.312	mg	supplier	wire	Gold (Au)	7440-57-5		0.312	mg	1000000	2033
encapsulation	Other Organic Materials	113.729	mg	supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		11.373	mg	100001	74091
encapsulation				supplier	mold compound	phenol resin	9003-35-4		5.687	mg	50005	37049
encapsulation				supplier	mold compound	Carbon Black	1333-86-4		1.137	mg	9997	7407
encapsulation				supplier	mold compound	Silica, vitreous	60676-86-0		90.982	mg	799989	592717
encapsulation				supplier	mold compound	Antimony Trioxide	1309-64-4		2.275	mg	20004	14821
encapsulation				JIG 1	mold compound	Brominated epoxy resin	68928-70-1		2.275	mg	20004	14821